

REMARKS

This responds to the Office Action mailed on July 14, 2005.

Claims 1-15, 18-20, 24 and 25 are allowed. Claim 16 is canceled; as a result, claims 1-15, 18-20, and 24-25 are pending in this application.

Double Patenting Rejection

Claim 16 was provisionally rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 21 and 22 of copending Application No. 10/071,743.

The Applicant has cancelled claim 16.

§102 Rejection of the Claims

Claim 16 was rejected under 35 USC § 102(e) as being anticipated by Jayaraman et al. (U.S. 2003/0153667).

The Applicant has cancelled claim 16.

Serial Number: 10/612,328

Dkt: 884.946US1 (INTEL)

Filing Date: June 30, 2003

Title: POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE APPLICATION

Assignee: Intel Corporation

Allowable Subject Matter

Claims 1-15, 18-20, and 24-25 were allowed.

Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney ((612) 373-6976) to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

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Date 8 September 05

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 8th day of September, 2005.

Amy Moriarty
Name

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